



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

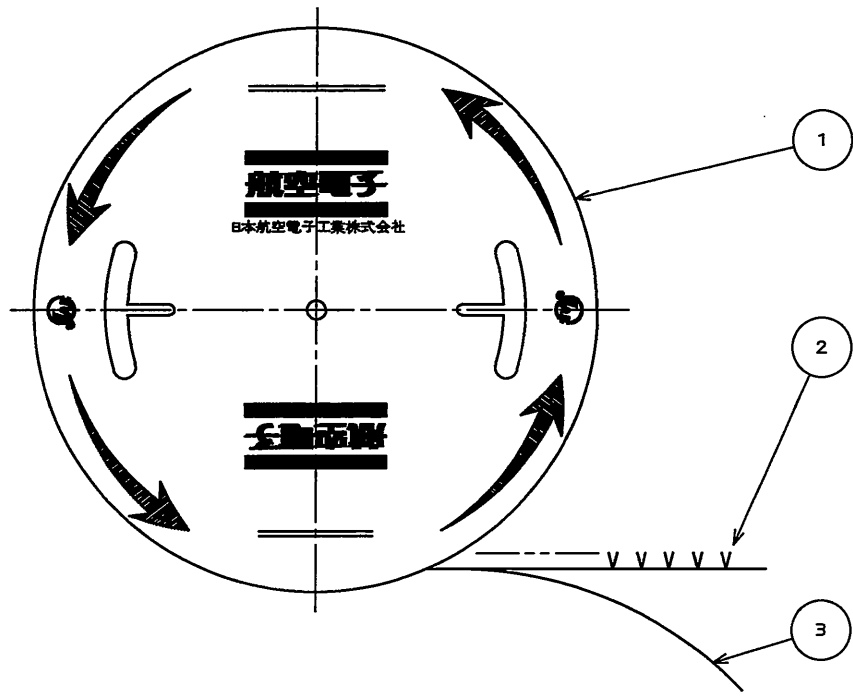
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

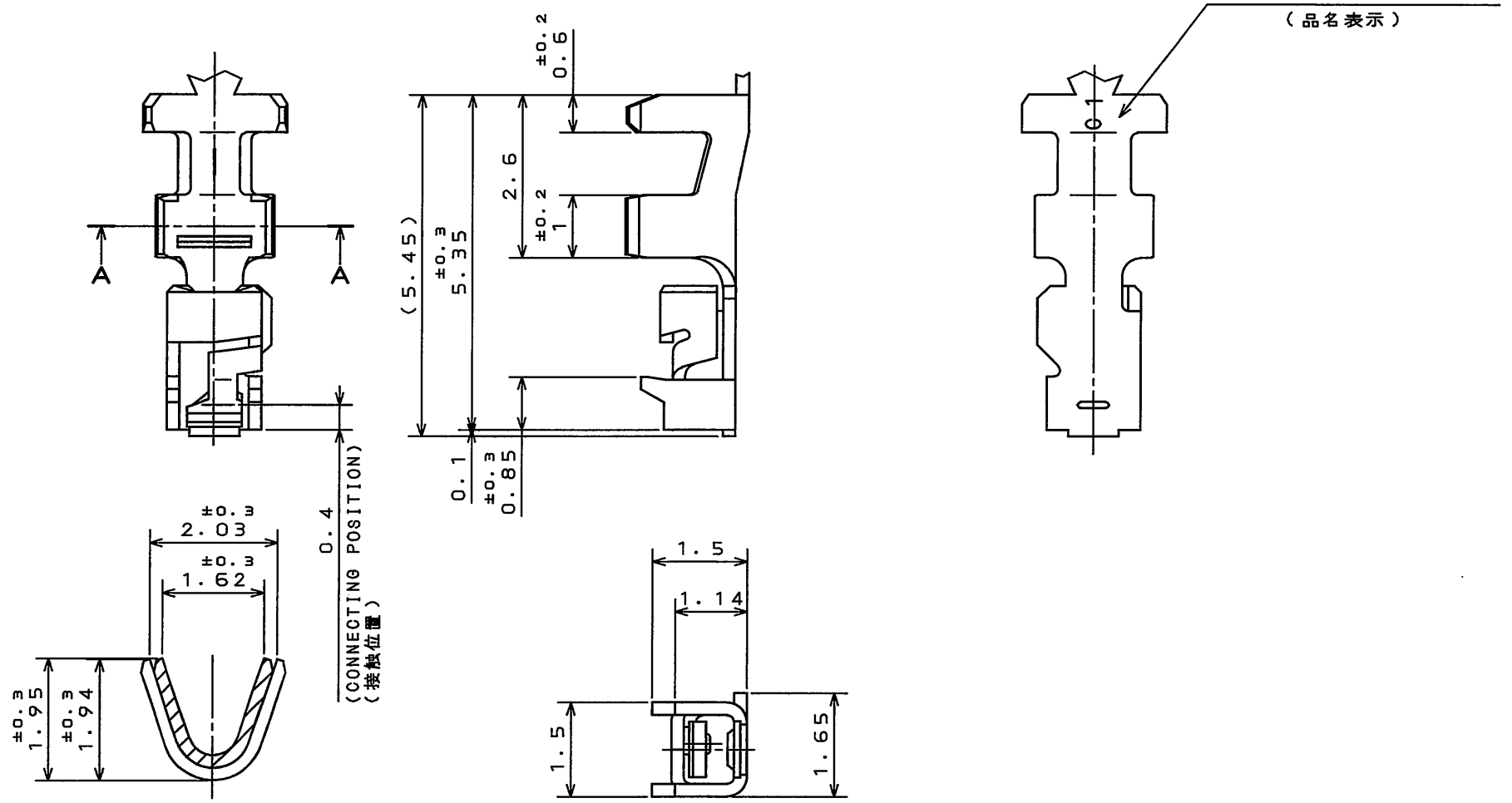


図面番号(DRAWING NO.) SJ100704

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	15.Jul.2010	070326	REVISED NOTE2	K.KIMURA	N.UCHIYAMA	—	y. MiguSawa



DETAIL CONTACT (SCALE 10:1)  
(コンタクト本体詳細図)



**DESIGNATION**  
命名法

LY10-C1-A1-10000

QUANTITY  
10000個のリール状

FINISH  
仕上

APPLICABLE WIRE (NOTE2)  
適合電線サイズ

CRIMP TYPE  
クリンプタイプ

SERIES  
シリーズ名

SECTION A-A  
(断面A-A)

EXCEPT CRIMPPOT  
(クリンプ部を除く)

- NOTE 1. INSERT PIN:  $0.5^{\pm 0.05}$  SQU.
- △ 2. APPLICABLE WIRE: #22~#26AWG, STRANDED.  
APPLICABLE WIRE INSULATION OUTER DIA:  $\phi 0.8 \sim \phi 1.3$   
(SEMI AUTOMATIC CRIMP MACHINE)
- 注 1 適合ピンは  $0.5^{\pm 0.05}$  である。
- △ 注 2 圧着適合電線サイズはAWG #22~#26の撚り線であり  
被覆外径寸法が  $\phi 0.8 \sim \phi 1.3$  のものである。(半自動圧着機)

3	PAPER TAPE	1	PAPER		
2	SOCKET CONTACT	10000	PHOSPHOR BRONZE	CRIMP AREA: GOLD FLASH OVER NICKEL CONTACT AREA: 0.1 $\mu$ m MIN GOLD PLATING OVER NICKEL	PITCH: 4.5
1	MAGAZINE	1	PAPER		
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
仕様書 (SPECIFICATION)	JACS-1337	第1版 (ORIGINAL DATE)	13.Feb.2004	尺度 (SCALE)	シリーズ (SERIES)
公差 (GENERAL TOLERANCE)		製図 DR.		名称 (TITLE)	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
寸法 (DIMENSION)	角度 (ANGLES)	担当 CHK.	N.UCHIYAMA	LY10-C1-A1-10000	JAE INDUSTRY, LTD.
. $\pm 0.8$	X° $\pm$	査閲 APPD.	K.KAWASE	MAGAZINE ASSEMBLY	
.X $\pm 0.4$	X°X' $\pm$	承認 APPD.	S.KASHIWA01	図面番号 (DRAWING NO.)	
.XX $\pm 0.1$				SJ100704	
.XXX $\pm$				質量 (MASS)	版数 (REV.)

DOF-0-212F(05.08)

